



Integrated Device Technology, Inc.  
2975 Stender Way, Santa Clara, CA - 95054

## PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: SM-0308-02      DATE: 8/15/2003  
Product Affected: 70121 / 70125 2Kx9 Dual-Port RAM

Date Effective: 11/15/2003

### MEANS OF DISTINGUISHING CHANGED DEVICES:

- ☒ Product Mark      Die revision "R" marked on top  
☐ Back Mark      of the part near the date code  
☐ Date Code  
☐ Other

Contact: Dennis Lantz

Title: Quality/Reliability Manager

Phone #: (831) 775-4032

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Attachment: ☒ Yes ☐ No

Samples: Available now

Contact your IDT Sales Representative

### DESCRIPTION AND PURPOSE OF CHANGE:

- ☒ Die Technology  
☐ Wafer Fabrication Process  
☐ Assembly Process  
☐ Equipment  
☐ Material  
☐ Testing  
☒ Manufacturing Site  
☐ Data Sheet  
☐ Other

To consolidate Wafer Fab production from Salinas, California (Fab 2) to Hillsboro, Oregon (Fab4). These qualified products will be transferred to IDT's Wafer Fab facility in Hillsboro, Oregon. These devices will be upgraded from Cmos 7 (.64um) to Cmos 8 (.60um). Cmos 8 is an existing qualified process at Fab 4.

### RELIABILITY/QUALIFICATION SUMMARY:

Qualification testing has been completed and verifies that there is no change to the product reliability. Qualification details are attached

### CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: \_\_\_\_\_

☐ *Approval for shipments prior to effective date.*

Name/Date: \_\_\_\_\_

E-Mail Address: \_\_\_\_\_

Title: \_\_\_\_\_

Phone# /Fax# : \_\_\_\_\_

### CUSTOMER COMMENTS:

### IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: \_\_\_\_\_

DATE: \_\_\_\_\_



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### ATTACHMENT - PCN #: SM-0308-02

**PCN Type:** Fab Site Change

**Data Sheet Change** None Expected

**Detail of Change** Transfer existing qualified products from Salinas, California Wafer Fab Facility (Fab 2) to Hillsboro, Oregon Wafer Fab Facility (Fab 4).

	Current Die Revision	Future Die Revision
Die Revision	V	R
Wafer Fab Tech	Cmos 7	Cmos 8
Wafer Size	6 inch	8 inch
# Poly Layers	2	2
# Metal Layers	2	2
Die Dimensions (sq mils)	11.96	10.92

#### Conversion Schedule (Estimated)

##### Base Device

70121S

70125S

##### Production Shipments and Sample Availability

Now

Now



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### ATTACHMENT - PCN #: SM-0308-02

#### Qualification Plan: QSM-0304-01

Test Vehicle	Test Results
<b>7132S4</b>	Sample Size/ # of Fails
Operating Life Test: Dynamic @+135°C, Vcc=4V for 750 hours	116 / 0
High Temp. Storage Life Test (Unbiased, 1000 hours @+150°C)	77 / 0
Bake & Ballshear Test @ 200°C / 4 ball bonds per device	5 / 0
Temperature Cycling: ( -65°C to +150°C, 500 cycles)	45 / 0
HAST: (Biased, 100 Hrs. @+130°C, +85%RH, 3 Atm.)	45 / 0
Autoclave:(Unbiased, 2 Atm Saturated Steam, +121°C, 168 Hrs)	45 / 0
ESD Human Body Model	9 / 0
ESD Charged Device Model	6 / 0
Latch up: ( Tested to 2X Vcc)	10 / 0